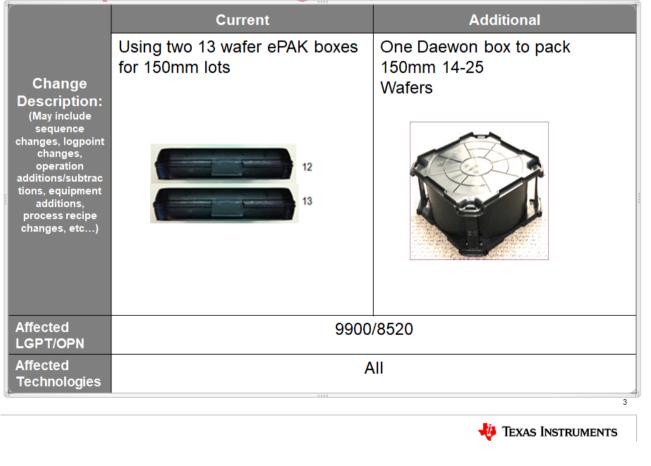
PCN Number:			20190624000.1				PCN Date:	June 27 2019			
Title: Introduction				of an alternate Wafer Ship box							
Customer Contact:			PCN Manager			Dept:		Qu	Quality Services		
Proposed 1 st Ship Da			ite:	te: Sept 27 2019							
Change Type:											
	Assembly Site				Assembly Process				Assembly Materials		
	Design				Electrical Specification				Mechanical Specification		
Test Site			\boxtimes	Packing/Shipping/Labeling				Test Process			
Wafer Bump Site					Wafer Bump Material				Wafer Bump Process		
Wafer Fab Site				Wafer Fab Materi	als			Wafer Fab Pro	cess		
					Part number cha	nge					

PCN Details

Description of Change:

This notice is to inform of an alternate new wafer sales shipping box for select wafer sales devices shown in the product affected section below. This new box may be used in conjunction the existing wafer ship box depending on the # of wafers ordered. For orders between 14 and 25 wafers, product will be shipped with this new wafer box. For orders of 13 or less wafers, the existing wafer box will be used. For orders between 26 and 38 wafers, both the existing and new box will be used to ship the order.

Description of Change



Reason for Change:

New Wafer box to reduce wafer box containers

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): None

Changes to product identification resulting from this PCN:

New Wafer box

Product Affected:

MPD23747-W	SN1110017YS	SN1402014YS	SN1612193YS
SN1002026YS	SN1208048YS	SN1507049YS	SN1703271YS
SN1006055YS	SN1311018YS	SN1509016YS	SN1705081YS
SN1109021YS	SN1311019YS	SN1612192YS	THS6212YS

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN ww admin team@list.ti.com